

# DDR3 Code Information

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## Module

### Part Number Decoder

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# Part Number Decoder

**M** X X X **B** X X X X X X X - X X X X X  
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## 1. Memory Module(M)

## 2. Module Configuration

3 : DIMM  
4 : SODIMM

## 3~4. Data bit

71 : x64 204pin Unbuffered SODIMM  
74 : x72 204pin ECC Unbuffered SODIMM  
78 : x64 240pin Unbuffered DIMM  
86 : x72 240pin LR DIMM  
90 : x72 240pin VLP Unbuffered DIMM  
91 : x72 240pin ECC Unbuffered DIMM  
92 : x72 240pin VLP Registered DIMM  
93 : x72 240pin Registered DIMM

## 5. DRAM Component Type

B : DDR3 SDRAM(1.5V VDD)

## 6~7. Depth

32 : 32M	33 : 32M (for 128Mb / 512Mb)
64 : 64M	65 : 64M (for 128Mb / 512Mb)
28 : 128M	29 : 128M (for 128Mb / 512Mb)
56 : 256M	57 : 256M (for 512Mb / 2Gb)
51 : 512M	52 : 512M (for 512Mb / 2Gb)
1G : 1G	1K : 1G (for 2Gb)
2G : 2G	2K : 2G (for 2Gb)
4G : 4G	8G : 8G

## 8. # of bank in Comp., Interface

7 : 8bank, SSTL(1.5V)

## 9. Bit Organization

0 : x4                      3 : x8  
4 : x16

## 10. Component Revision

M : M-die	A : A-die
B : B-die	C : C-die
D : D-die	E : E-die
F : F-die	G : G-die

## 11. Package

Z : FBGA (Lead-Free)  
H : FBGA (Lead-Free & Halogen-Free)  
J : FBGA (Lead-Free, DDP)  
M : FBGA (Lead-Free & Halogen-Free, DDP)  
B : FBGA (Lead-Free & Halogen-Free, Flip Chip)  
E : FBGA (Lead-Free & Halogen-Free, QDP)  
O : FBGA (Lead-Free & Halogen-Free, QDP for 64GB LRDIMM)

## 12. PCB Revision

0 : None	1 : 1st Rev.
2 : 2nd Rev.	3 : 3rd Rev.
4 : 4th Rev.	S : Reduced Layer

## 13. "-"

## 14. Temp & Power

C : Commercial Temp (0°C ~ 85°C), Normal Power (1.5V)  
Y : Commercial Temp (0°C ~ 85°C), Low VDD (1.35V)

## 15~16. Speed

F7 : DDR3-800 (400MHz@CL=6, tRCD=6, tRP=6)  
F8 : DDR3-1066 (533MHz@CL=7, tRCD=7, tRP=7)  
H9 : DDR3-1333 (667MHz@CL=9, tRCD=9, tRP=9)  
K0 : DDR3-1600 (800MHz@CL=11, tRCD=11, tRP=11)  
MA : DDR3-1866 (933MHz@CL=13, tRCD=13, tRP=13)

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## 17. Memory Buffer

- 0 : Inphi iMB02-GS02A
- 1 : IDT A2 (Greendale)
- 2 : Montage MB C0
- 3 : Inphi iMB02-GS02B
- 4 : Montage MC CI